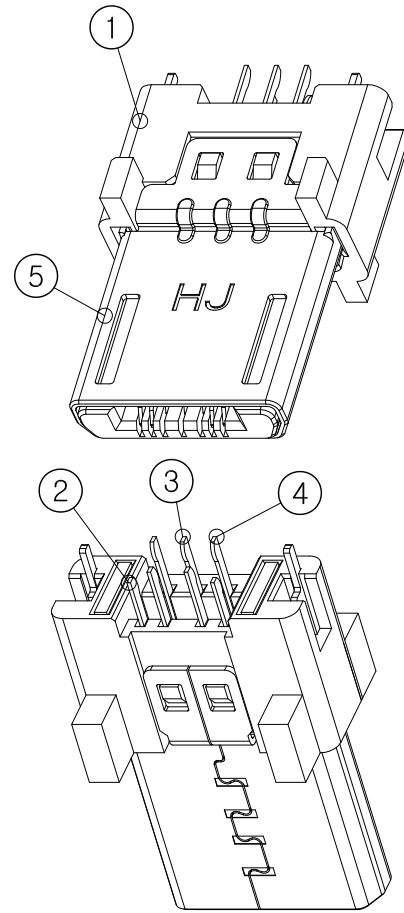
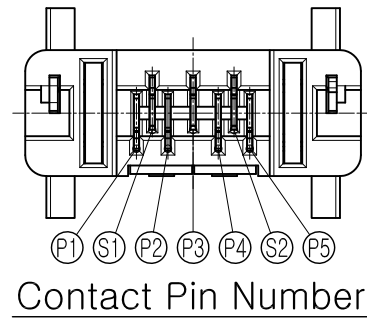
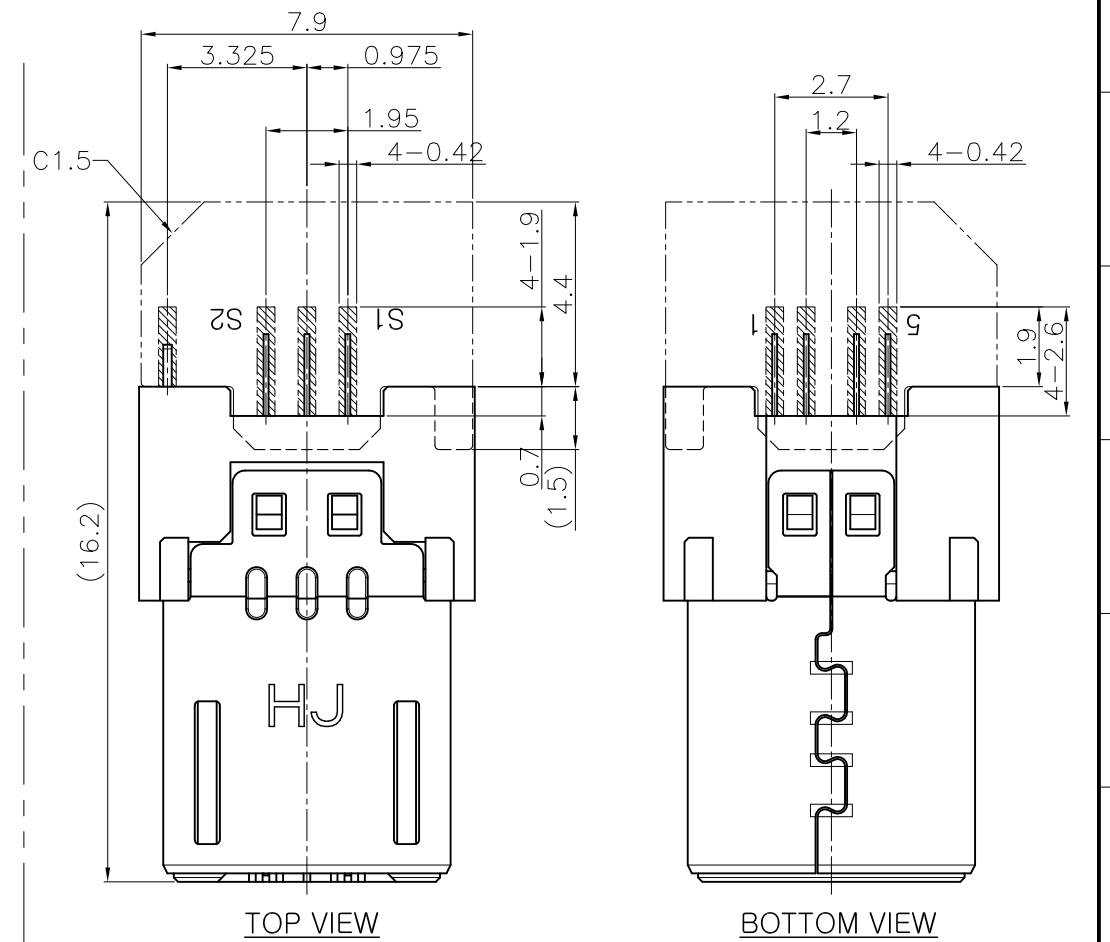


※ NOTE

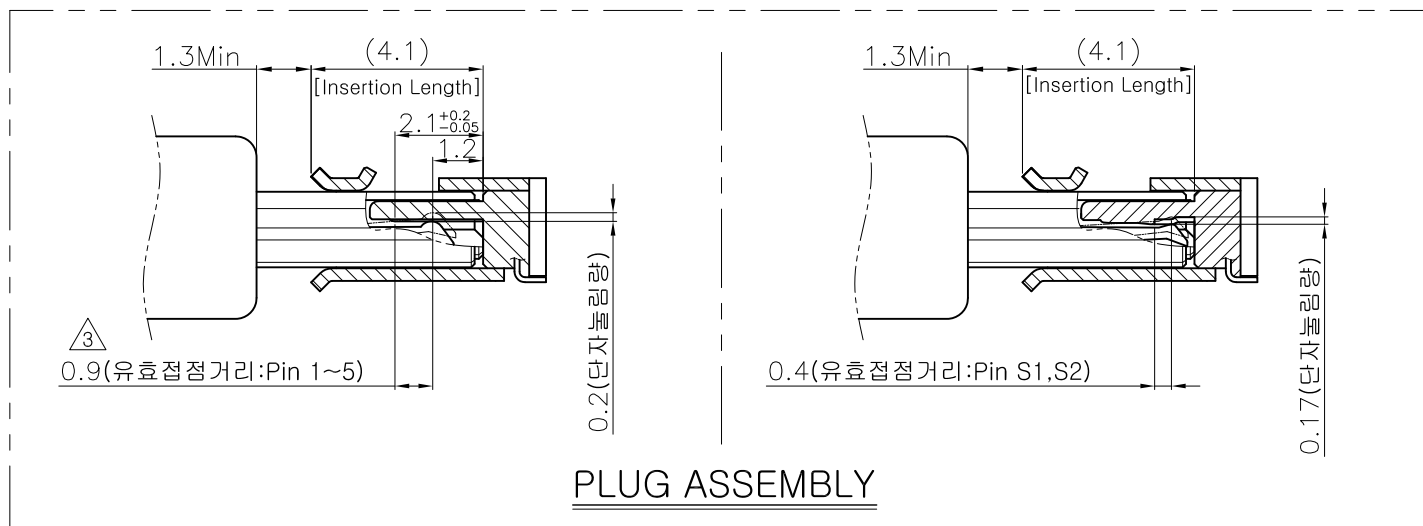
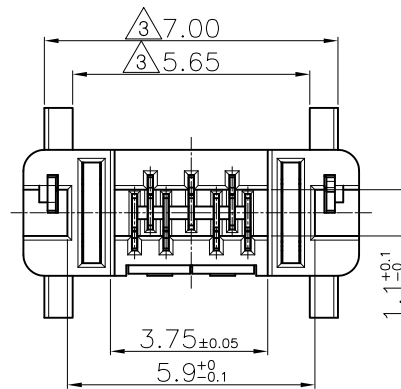
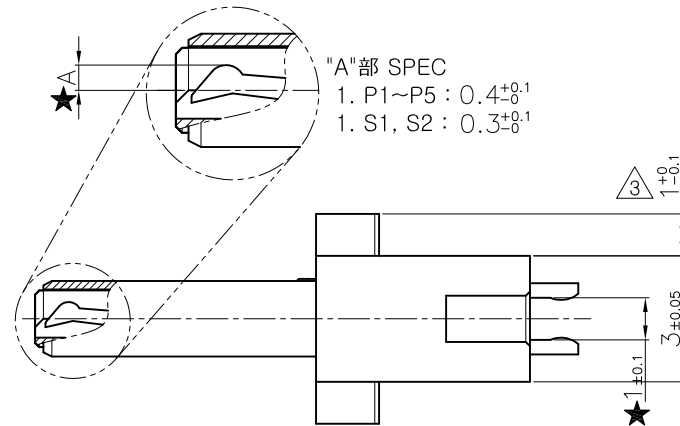
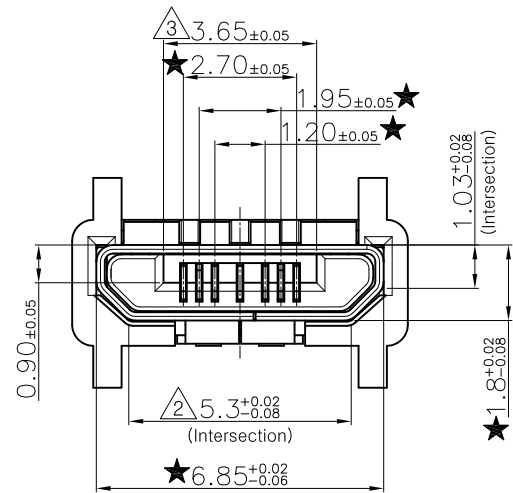
1. PLATING
  - 1) CONTACT A&B
    - Contact Area : Au 0.75 $\mu$ m over Ni 2.0~5.0 $\mu$ m
    - Lead Area : Au 0.05 $\mu$ m over Ni 0.2~3.0 $\mu$ m
  - 2) METAL COVER : Ni 1.0~5.0 $\mu$ m
2. ★ : C.T.Q



Rev No.	Description of Revision	Date	Name	Approved	ECN No.
① X 1	공정용 변경	2008.11.03	이영근	최경용	081103-02
② X 1	인입부 형상 변경 (고객 요청)	2009.01.12	이영근	최경용	090112-01
③ X 8	삼성 공정 불량 개선	2009.04.02	이영근		



PCB ASSEMBLY  
(General Tolerance :  $\pm 0.05$ )



5	METAL COVER	STS304	Note. 1	t0.2
4	CONTACT S	C7025	Note. 1	t0.12
3	CONTACT B	C7025	Note. 1	t0.12
2	CONTACT A	C7025	Note. 1	t0.12
1	HOUSING	LCP	Black Color	UL94V-0
No	Descriptions	Material	Finish	Remarks

General Tolerance		Scale	Units	mm	Sheet
Dimension	mm (°)	Date	2008. 06. 11		1 of 1
X	$\pm 0.2$	Drawn	Design	Checked	Reviewed
X.X	$\pm 0.1$	Y. K. LEE			
X.XX	$\pm 0.05$				
X.XXX	$\pm 0.01$				
ANGLE	$\pm 1^\circ$				

TITLE		HY07-AC0710	
△Micro USB 공정용 Plug		Customer Drawing	
SW No.		Rev.	3
DWG No.	HY07-AC0710-A1		

HJ&C HYUP JIN I&C CO., LTD.